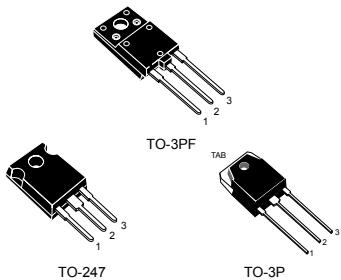
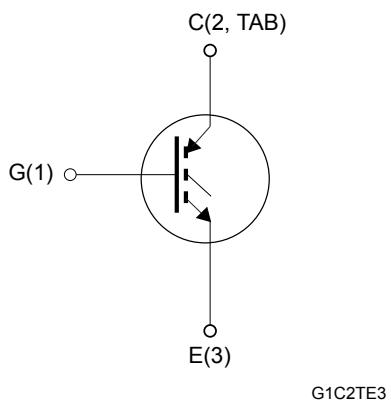


Trench gate field-stop IGBT, HB series 650 V, 20 A high speed



Features

- Maximum junction temperature: $T_J = 175 \text{ }^{\circ}\text{C}$
- High speed switching series
- Minimized tail current
- $V_{CE(\text{sat})} = 1.55 \text{ V (typ.)} @ I_C = 20 \text{ A}$
- Tight parameters distribution
- Safe paralleling
- Low thermal resistance



Applications

- Photovoltaic inverters
- Power factor correction
- Welding
- High-frequency converters

Description

These devices are IGBTs developed using an advanced proprietary trench gate field-stop structure. These devices are part of the new HB series of IGBTs, which represent an optimum compromise between conduction and switching loss to maximize the efficiency of any frequency converter. Furthermore, the slightly positive $V_{CE(\text{sat})}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.



Product status links

STGFW20H65FB
STGW20H65FB
STGWT20H65FB

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-247, TO-3P	TO-3PF	
V _{CES}	Collector-emitter voltage ($V_{GE} = 0$ V)	650		V
I _C	Continuous collector current at $T_C = 25$ °C	40		A
	Continuous collector current at $T_C = 100$ °C	20		A
I _{CP} ⁽¹⁾	Pulsed collector current	80		A
V _{GE}	Gate-emitter voltage	±20		V
P _{TOT}	Total power dissipation at $T_C = 25$ °C	168	52	W
T _{stg}	Storage temperature range	-55 to 150		°C
T _J	Operating junction temperature range	-55 to 175		°C

1. Pulse width is limited by maximum junction temperature.

Table 2. Thermal data

Symbol	Parameter	Value		Unit
		TO-247, TO-3P	TO-3PF	
R _{thJC}	Thermal resistance junction-case	0.9	2.9	°C/W
R _{thJA}	Thermal resistance junction-ambient	50		°C/W

2 Electrical characteristics

$T_J = 25^\circ\text{C}$ unless otherwise specified

Table 3. Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}, I_C = 2 \text{ mA}$	650			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_C = 20 \text{ A}$		1.55	2	V
		$V_{GE} = 15 \text{ V}, I_C = 20 \text{ A}, T_J = 125^\circ\text{C}$		1.65		
		$V_{GE} = 15 \text{ V}, I_C = 20 \text{ A}, T_J = 175^\circ\text{C}$		1.75		
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1 \text{ mA}$	5	6	7	V
I_{CES}	Collector cut-off current	$V_{GE} = 0 \text{ V}, V_{CE} = 650 \text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current	$V_{CE} = 0 \text{ V}, V_{GE} = \pm 20 \text{ V}$			250	nA

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance		-	2764	-	pF
C_{oes}	Output capacitance	$V_{CE} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GE} = 0 \text{ V}$	-	80	-	pF
C_{res}	Reverse transfer capacitance		-	60	-	pF
Q_g	Total gate charge		-	120	-	nC
Q_{ge}	Gate-emitter charge	$V_{CC} = 520 \text{ V}, I_C = 20 \text{ A}, V_{GE} = 0 \text{ to } 15 \text{ V}$ (see Figure 26. Gate charge test circuit)	-	20	-	nC
Q_{gc}	Gate-collector charge		-	50	-	nC

Table 5. Switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 20 \text{ A},$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V}$ (see Figure 25. Test circuit for inductive load switching)	-	30	-	ns
t_r	Current rise time		-	11	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1400	-	A/ μ s
$t_{d(off)}$	Turn-off delay time		-	139	-	ns
t_f	Current fall time		-	20	-	ns
$E_{on}^{(1)}$	Turn-on switching energy		-	77	-	μ J
$E_{off}^{(2)}$	Turn-off switching energy		-	170	-	μ J
E_{ts}	Total switching energy		-	247	-	μ J
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 20 \text{ A},$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V}, T_J = 175 \text{ }^\circ\text{C}$ (see Figure 25. Test circuit for inductive load switching)	-	29	-	ns
t_r	Current rise time		-	12	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1352	-	A/ μ s
$t_{d(off)}$	Turn-off-delay time		-	147	-	ns
t_f	Current fall time		-	38	-	ns
$E_{on}^{(1)}$	Turn-on switching energy		-	88	-	μ J
$E_{off}^{(2)}$	Turn-off switching energy		-	353	-	μ J
E_{ts}	Total switching energy		-	441	-	μ J

1. Including the reverse recovery of the external SiC diode STPSC206W.

2. Including the tail of the collector current.

2.1

Electrical characteristics (curves)

Figure 1. Output characteristics ($T_J = 25^\circ\text{C}$)

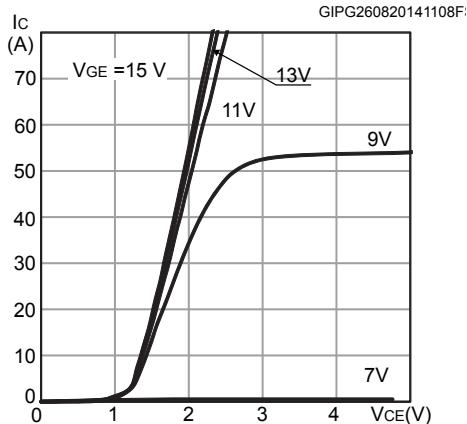


Figure 2. Output characteristics ($T_J = 175^\circ\text{C}$)

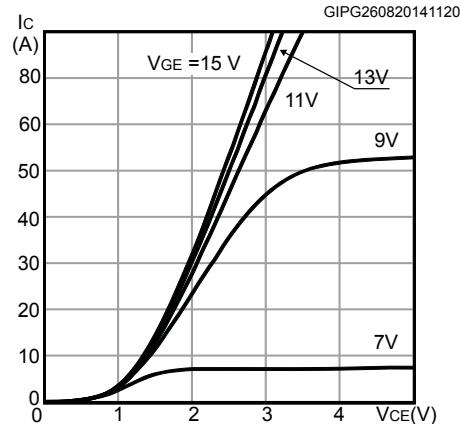


Figure 3. Transfer characteristics

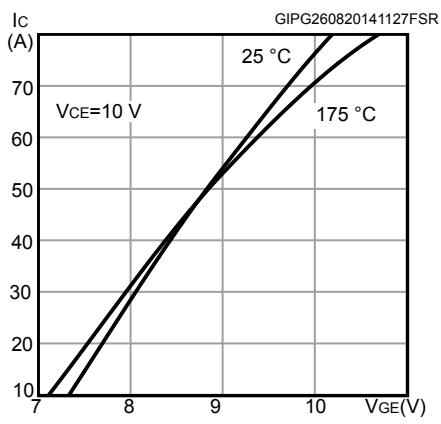


Figure 4. Collector current vs case temperature for TO-247 and TO-3P

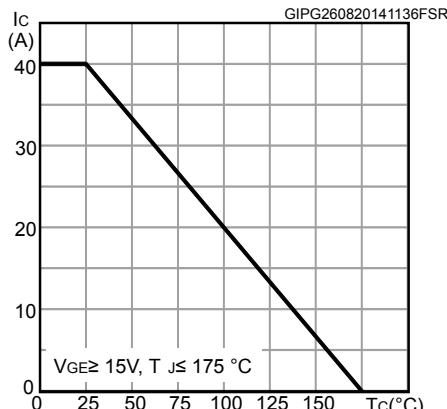


Figure 5. Collector current vs case temperature for TO-3PF

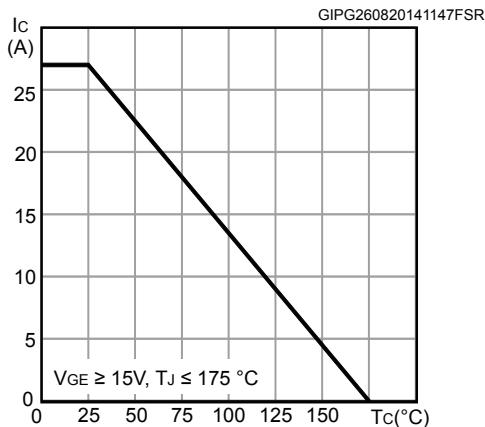


Figure 6. $V_{CE(\text{sat})}$ vs junction temperature

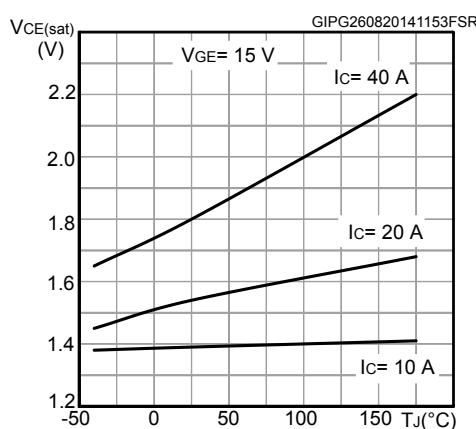


Figure 7. Power dissipation vs case temperature for TO-247 and TO-3P

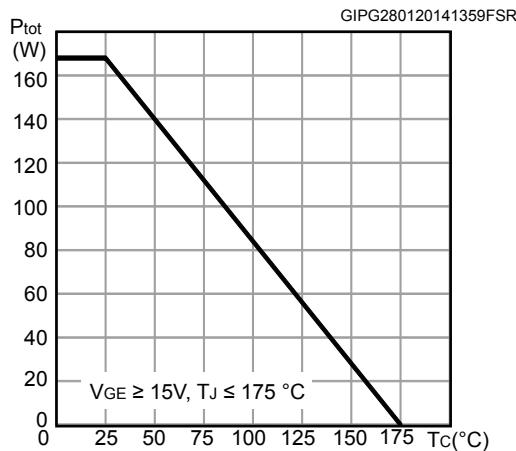


Figure 8. Power dissipation vs case temperature for TO-3PF

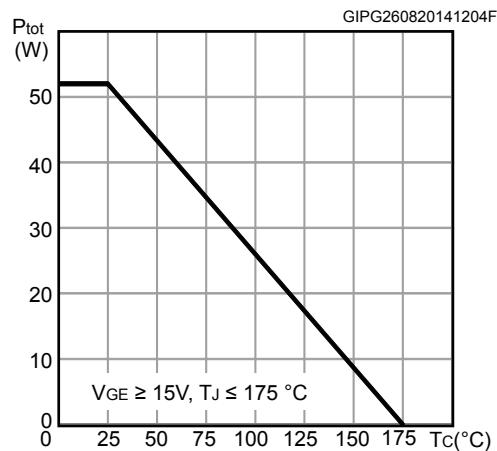


Figure 9. Forward bias safe operating area for TO-247 and TO-3P

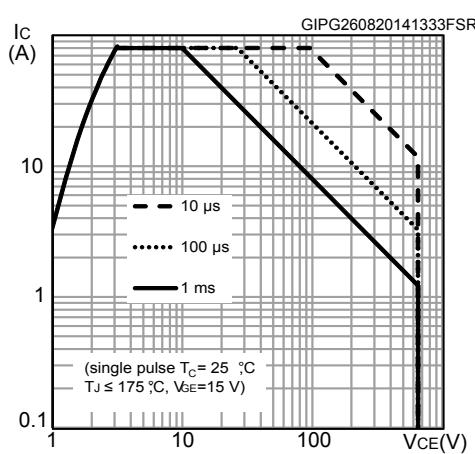


Figure 10. Forward bias safe operating area for TO-3PF

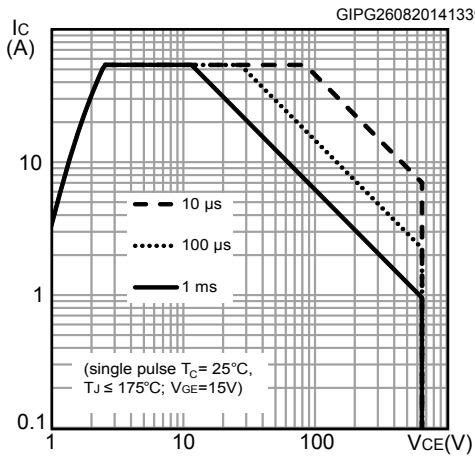


Figure 11. Collector current vs. switching frequency for TO-247 and TO-3P

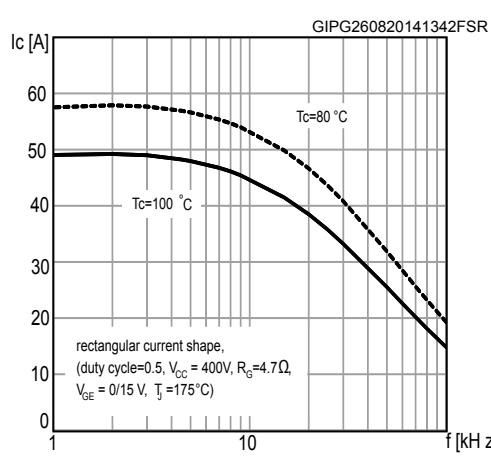


Figure 12. Collector current vs. switching frequency for TO-3PF

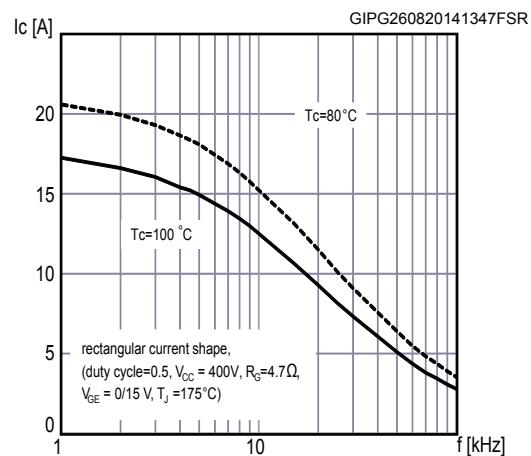


Figure 13. Normalized $V_{GE(th)}$ vs junction temperature

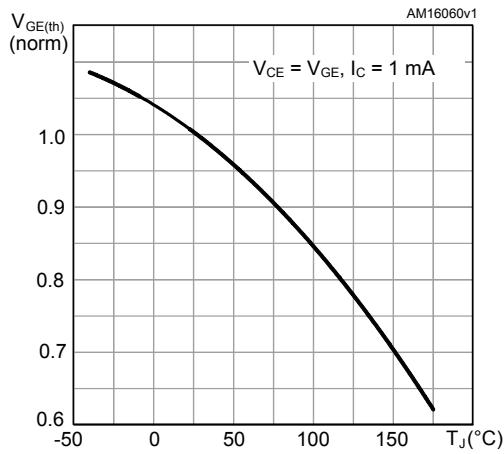


Figure 14. Normalized $V_{(BR)CES}$ vs junction temperature

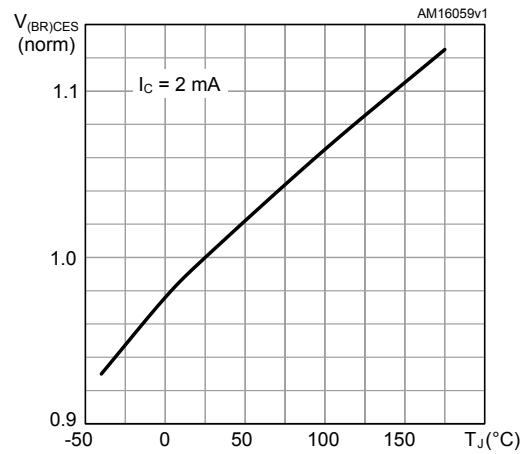


Figure 15. Switching energy vs temperature

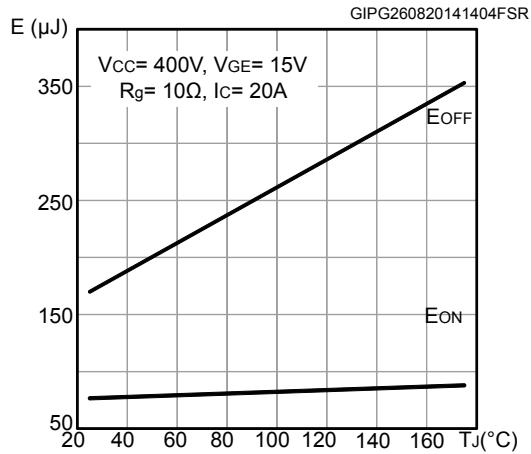


Figure 16. Switching energy vs gate resistance

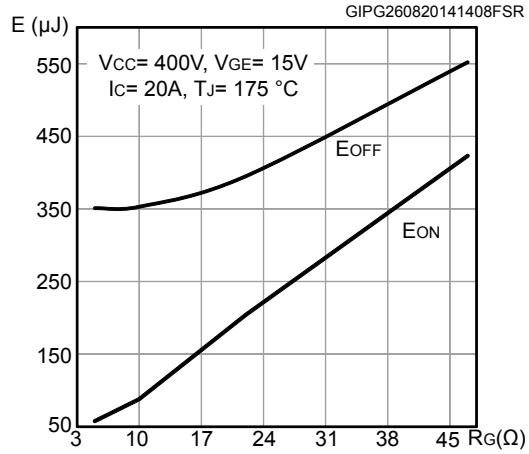


Figure 17. Switching energy vs collector current

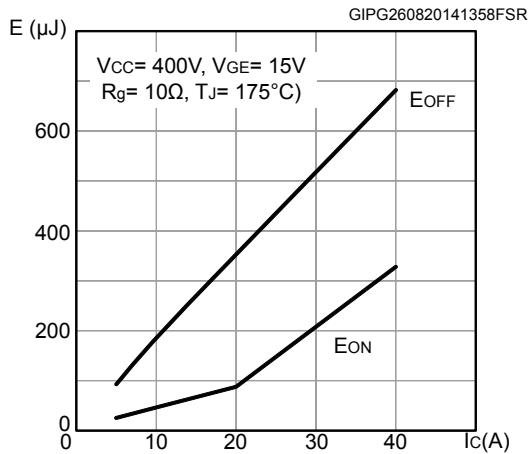


Figure 18. Switching energy vs collector emitter voltage

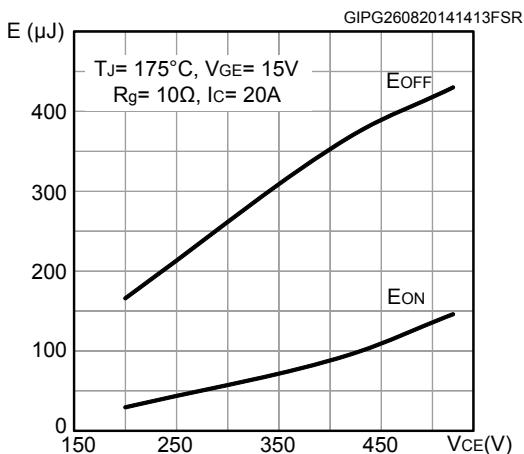


Figure 19. Switching times vs collector current

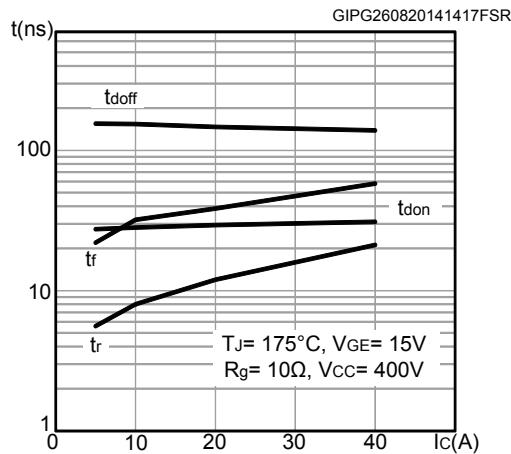


Figure 20. Switching times vs gate resistance

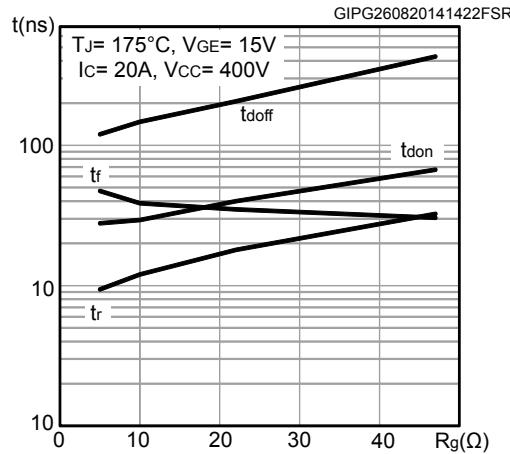


Figure 21. Capacitance variations

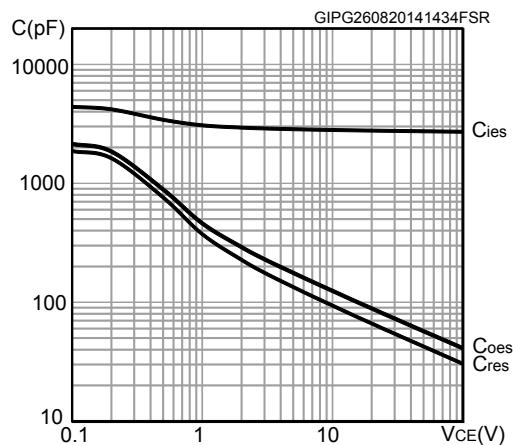


Figure 22. Gate charge vs gate-emitter voltage

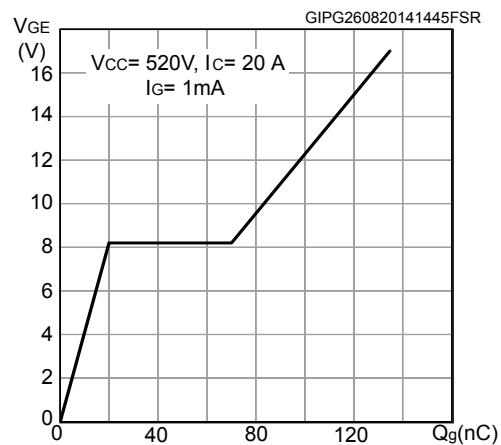


Figure 23. Thermal impedance for TO-247 and TO-3P

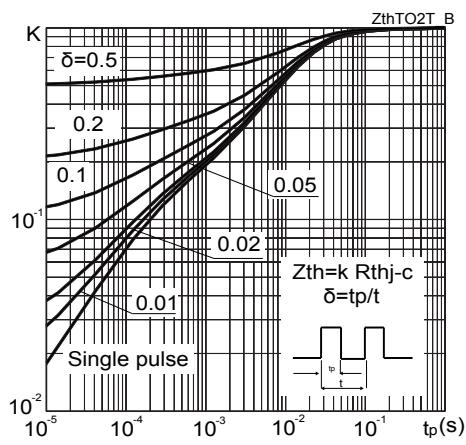
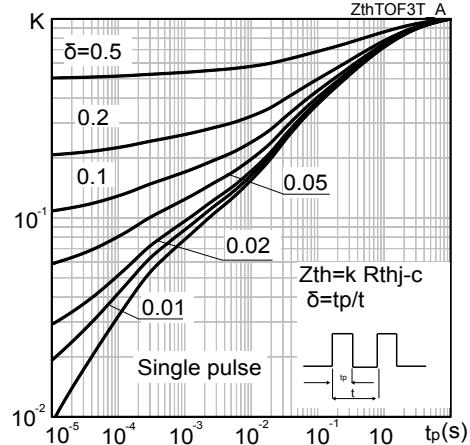


Figure 24. Thermal impedance for in TO-3PF



3

Test circuits

Figure 25. Test circuit for inductive load switching

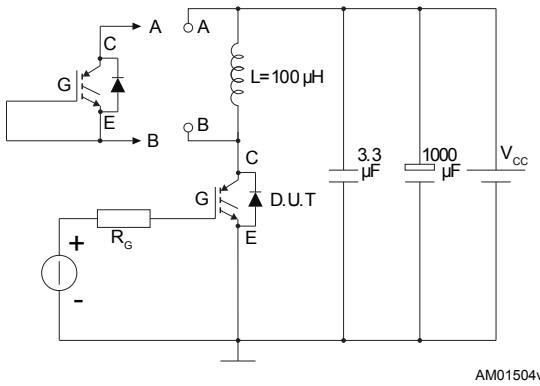


Figure 26. Gate charge test circuit

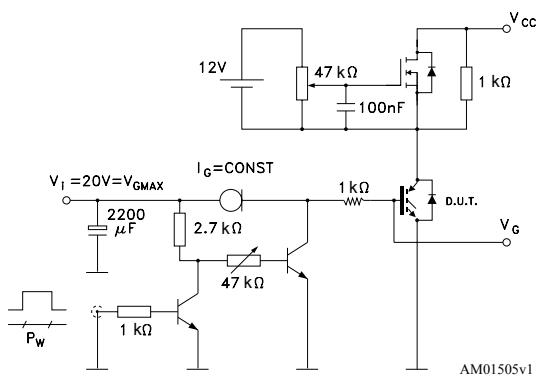


Figure 27. Switching waveform

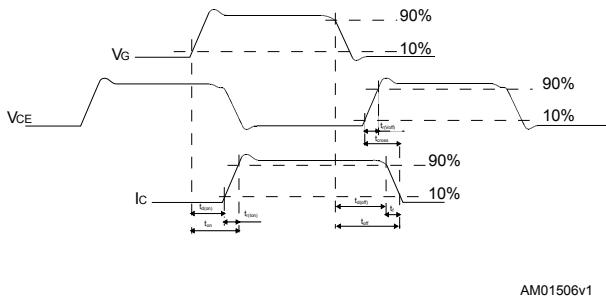
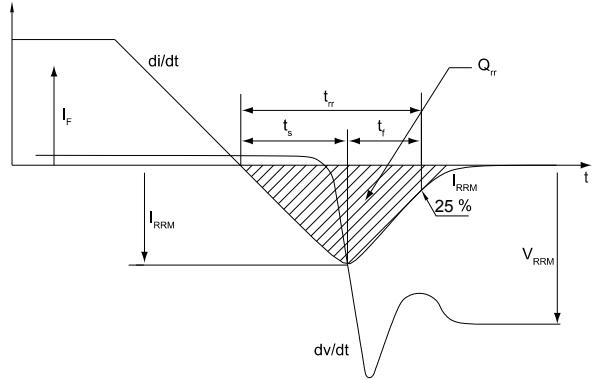


Figure 28. Diode reverse recovery waveform

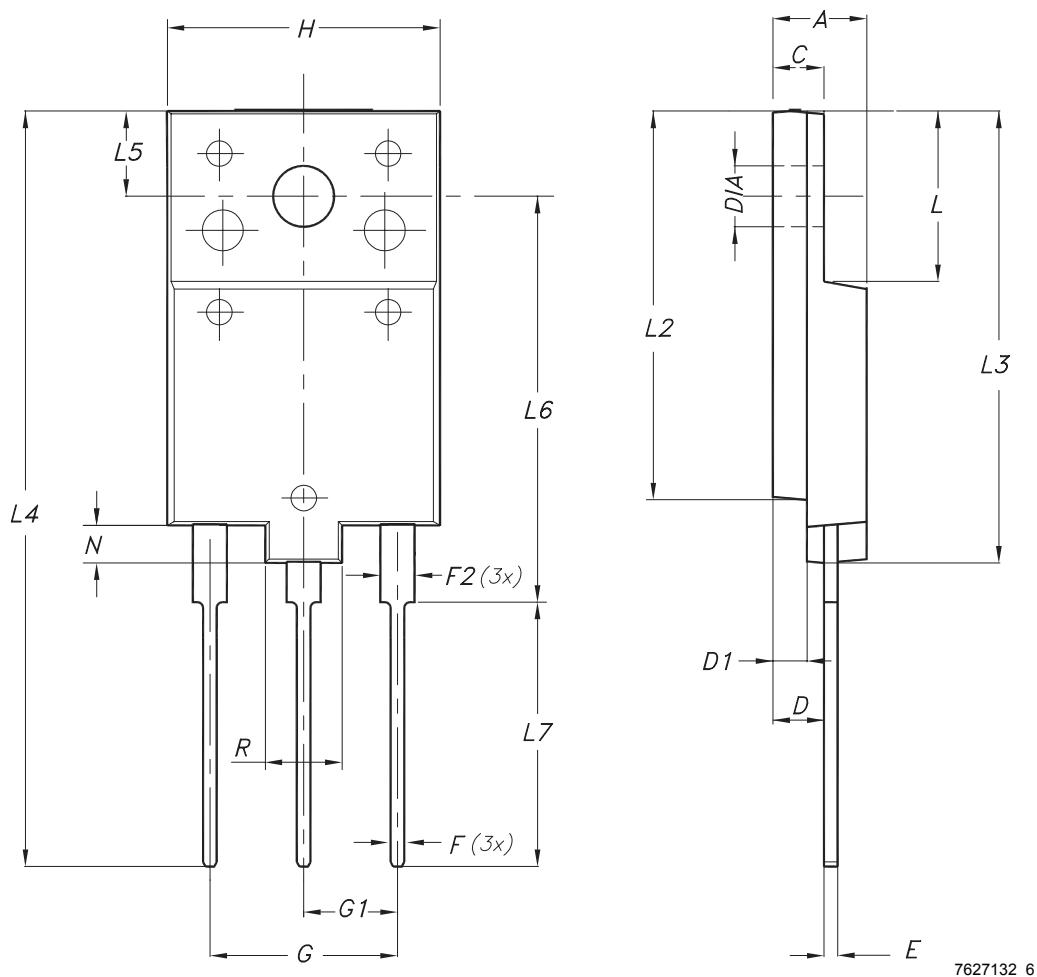


4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-3PF package information

Figure 29. TO-3PF package outline



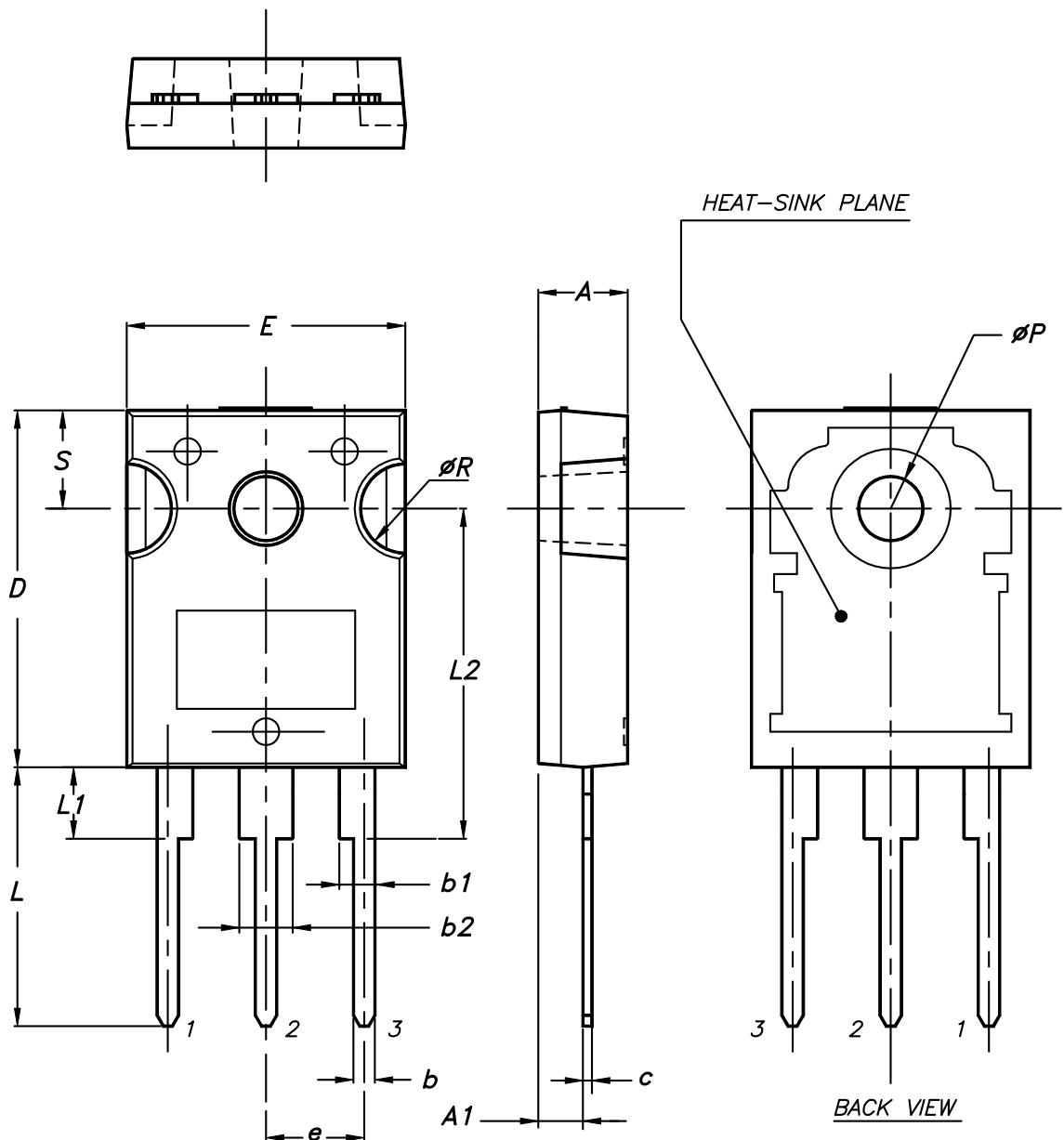
7627132_6

Table 6. TO-3PF mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.10
F	0.65		0.95
F2	1.80		2.20
G	10.30		11.50
G1		5.45	
H	15.30		15.70
L	9.80	10.00	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.20		44.40
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15.00
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

4.2 TO-247 package information

Figure 30. TO-247 package outline



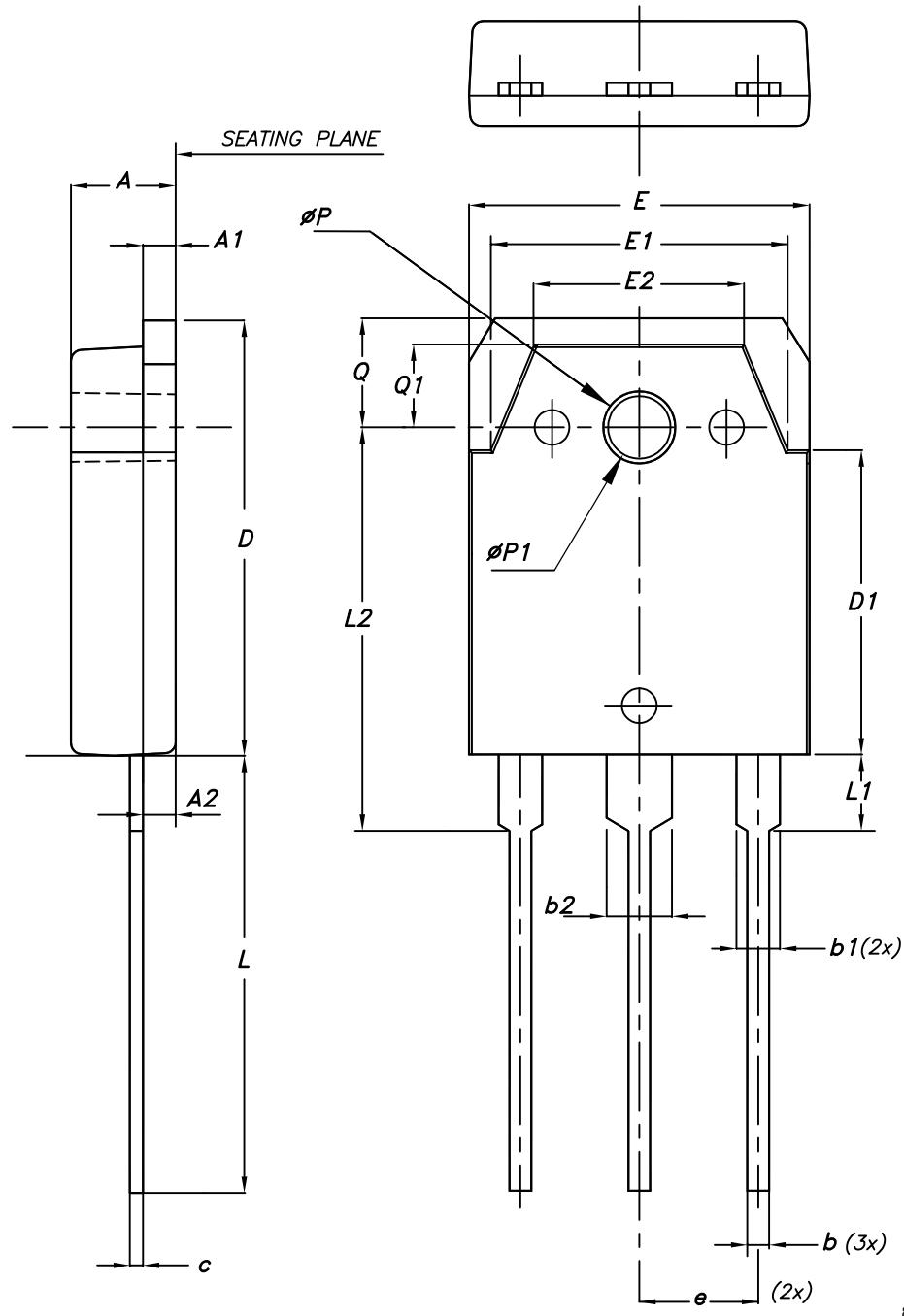
0075325_9

Table 7. TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

4.3 TO-3P package information

Figure 31. TO-3P package outline



8045950_3

Table 8. TO-3P package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.60	4.80	5.00
A1	1.45	1.50	1.65
A2	1.20	1.40	1.60
b	0.80	1.00	1.20
b1	1.80	2.00	2.20
b2	2.80	3.00	3.20
c	0.55	0.60	0.75
D	19.70	19.90	20.10
D1	13.70	13.90	14.10
E	15.40	15.60	15.80
E1	13.40	13.60	13.80
E2	9.40	9.60	9.90
e	5.15	5.45	5.75
L	19.80	20.00	20.20
L1	3.30	3.50	3.70
L2	18.20	18.40	18.60
ØP	3.30	3.40	3.50
ØP1	3.10	3.20	3.30
Q	4.80	5.00	5.20
Q1	3.60	3.80	4.00

5 Ordering information

Table 9. Order codes

Order code	Marking	Package	Packing
STGFW20H65FB	G20H65FB	TO-3PF	Tube
STGW20H65FB	GW20H65FB	TO-247	
STGWT20H65FB	GWT20H65FB	TO-3P	

Revision history

Table 10. Document revision history

Date	Revision	Changes
28-Aug-2014	1	Initial release.
15-Apr-2020	2	Updated applications in cover page. Updated Table 9. Order codes . Minor text changes.

Contents

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